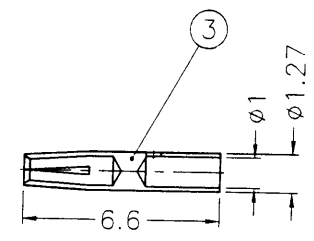
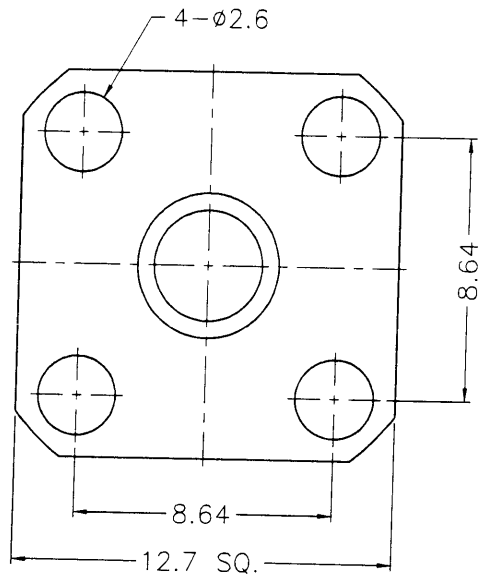
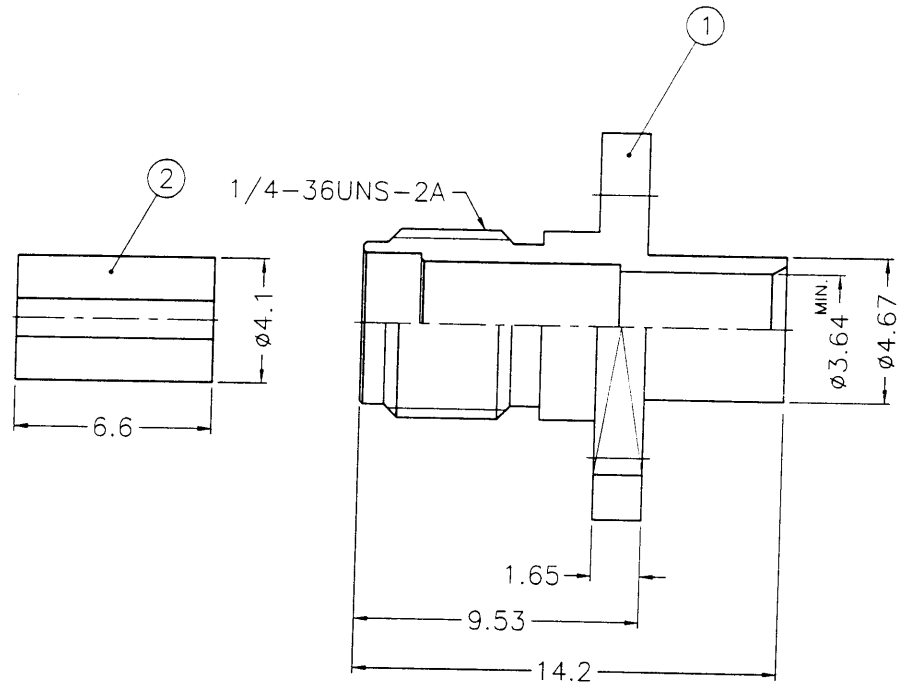
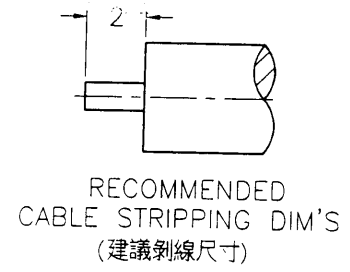


1 2 3 4 5 6 7 8

REVISIONS			
ISS	ZONE	DESCRIPTION\PER REQUEST\DATE	
B	A-1	NO.3 WAS CHANGED\RD-DM89103101Y\10-31-00'	

業務部



- NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)
- BRASS PER QQ-B-626
 - GOLD PL. 3 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 - BERYLLIUM COPPER PER QQ-C-530
 - GOLD PL. 50 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 - TEFLON MIL-P-19468

出圖
2000. 11. 04
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1. CONTACT PIN TO SOLDER

DIMENSIONS ARE IN MILLIMETERS					PART NO.		Amphenol - Kai Jack			
UNLESS OTHERWISE SPECIFIED TOLERANCES					APPROVED		TAINAN TAIWAN			
3	CONTACT PIN	NOTE 3	NOTE 4	1	SMA7081-3-127/1-B		DATE	10-27-00'	TITLE	SMA SEMI-RIGID PANEL JACK
2	INSULATOR	NOTE 5	NATURAL	1	SMA7081-2T-50		DATE	10-27-00'	DRAWING NO.	KJ-SMA6581A1-3GT50G-.141-50
1	BODY	NOTE 1	NOTE 2	1	SMA7581-1-467/364-C		DATE	10-27-00'	FILE NO.	F:\DWG\SMA\6581A1\141-50\3GT50G
NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.	SCALE	4/1	ISSUE	B	